

OE-A Members – Companies



- A** ABeetle (TW)
Almax (US)
Alpha Assembly Solutions (US)
Amires (CZ)
- B** BASF Coatings Schweiz (CH)
Bayflex (US)
BeLink (FR)
Beneli (SE)
BotFactory (US)
Brewer Science (US)
Brückner Maschinenbau (DE)
BST (DE)
- C** CCI Eurolam (DE)
Celanese (UK)
Chasm Advanced Materials (US)
Classic Stripes (IN)
Coatema Coating Machinery (DE)
CondAlign (NO)
Continental (DE)
Copprint (IL)
Coruna Printed Electronics (CH)
- D** Dai Nippon Printing (JP)
db-matik (DE)
DoMicro (NL)
Dorey Converting Systems (FR)
Dracula Technologies (FR)
- E** E2IP (CA)
Eastman Chemical (DE)
E Ink (US)
Elantas Europe (DE)
Elmeric (DE)
Enfucell (FI)
Enjet (KR)
Eptatech (IT)
Ersa (DE)
Exakt Advanced Technologies (DE)
- F** Felix Böttcher (DE)
Felix Schoeller Holding (DE)
Fleep Technologies (IT)
FlexEnable Technology (GB)
Folex Coating (DE)
FUELIUM (ES)
Fujifilm Dimatix (US)
- G** GenesInk (FR)
Greiner Innoventures (AT)
Guangdong Juhua Printing (CN)
- H** Hamamatsu Photonics (DE)
H.C. Moog (DE)
Heidelberg Printed Electronics (DE)
Heliatek (DE)
Henkel (DE)
- Heraeus Deutschland (DE)
Hoffmann + Krippner (DE)
HumminK (FR)
- I** IBS Precision Engineering (NL)
IEE (LU)
Industrial Print Solutions (DE)
Innovation Horizons (CH)
Innovation Lab (DE)
Inoptec (DE)
Interlink Electronics (US)
Iscent (FI)
ISORG (FR)
- J** JT International Germany (DE)
JiLin OLED Material Tech (CN)
- K** Kelenn Technology (FR)
KETMarket (DE)
Kroenert (DE)
KSG (DE)
- L** Lambda Technology (DE)
Leonhard Kurz Stiftung (DE)
LinkZill (CN)
Liquid Wire (US)
Lohmann (DE)
- M** Manz (DE)
Merconics (DE)
Metafas, NL
MGI – Ceradrop (FR)
Mimotype Technologies (DE)
MMP Premium Printing Center (DE)
Molecular Plasma Group (LU)
MSW (DE)
- N** Nano-C (US)
Neto Innovation (FR)
New Cable Corporation (FI)
Normandy Coating (FR)
NovaCentrix (US)
nsm Norbert Schläfli (CH)
NXT (DE)
- O** OLEDWorks (DE)
Organic Electronic Technologies (GR)
Oxford Photovoltaics (GB)
- P** Piezotech (FR)
PolyIC (DE)
PragmatIC Semiconductor (GB)
Printcolor Deutschland (DE)
Printed Electronics (GB)
Pulseforge (US)
Pütz Folien (DE)
PVF Mesh & Screen Technology (DE)
- Q** Quad Industries (BE)
- R** RK Siebdrucktechnik (DE)
- S** SAES Getters (IT)
SAIT Europe (GB)
Saralon (DE)
Schreiner Group (DE)
Screentec (FI)
Seristampa (IT)
SmartKem (UK)
Smooth & Sharp Corp. (TW)
Spin Corporation (JP)
Sun Chemical (US)
Symbio (FR)
- T** Tacterion (DE)
Tactotek (FI)
Teknek (GB)
Tesa (DE)
TracXon (NL)
TSE Troller (CH)
- U** Universal Display Corp. (US)
- V** VARTA Microbattery (DE)
VFP Ink Technologies (FR)
Vitzrocell, (KR)
- W** Werner Blase (DE)
Witte Technology (DE)
- X** X-Celeprint (IE)
Xenon Corporation (US)
Xiamen Funano New Material (CN)
XTPL (PL)
Xymox Technologies (US)
- Y** Ynvisible (PT)
YTC America (US)

- A** AIT – Austrian Institute of Technology (AT)
AlmaScience (PT)
Aristotle University of Thessaloniki LTFN (GR)
- B** BRNO University of Technology (CZ)
- C** CEA Liten (FR)
Centi - Centre for Nanotechnology & Smart Materials (PT)
Centre Technique du Papier (CTP) (FR)
CIDETEC (ES)
Consiglio Nazionale delle Ricerche (CNR) (IT)
CPI - Centre for Process Innovation (GB)
CSEM (CH)
CSIR (ZA)
- D** Danish Technological Institute (DK)
- E** Eindhoven University of Technology (NL)
EMPA (CH)
ESA (GB)
Eurecat (ES)
- F** Fontys University of Applied Sciences (NL)
Fraunhofer EMFT (DE)
Fraunhofer ENAS (DE)
Fraunhofer FEP (DE)
Fraunhofer IAP (DE)
Fraunhofer IFAM (DE)
Fraunhofer ILT (DE)
Fraunhofer IPA (DE)
Fraunhofer ISC (DE)
Fraunhofer ISE (DE)
Friedrich-Alexander-Universität – WW6 – i-Meet (DE)
Friedrich Schiller Universität Jena (DE)
- H** Hahn-Schickard-Gesellschaft für angewandte Forschung (DE)
Hochschule der Medien - IAF, IAD (DE)
Hochschule München University of Applied Sciences (DE)
Hochschule Niederrhein (DE)
Holst Centre (NL)
- I** ICI – Printability and Graphic Communications Institute (CA)
Imperial College London – Centre for Plastic Electronics (GB)
Institut für Mikroelektronik Stuttgart (DE)
IPC – Technical Centre of Plastics Engineering (FR)
IU Internationale Hochschule (DE)
- J** Joanneum Research (AT)
Johannes Kepler Universität Linz - LIOS (AT)
- K** Karlsruhe Institute of Technology - LTI (DE)
- L** Landshut University of Applied Sciences (DE)
Leitat Technological Center (ES)
Loughborough University (GB)
- M** MINES Saint-Étienne – Microelectronics - Center of Provence (FR)
- N** NAITEC (ES)
National Research Council Canada (CA)
- O** Oulu University of Applied Sciences (FI)
- P** Profactor (AT)
- R** RISE Research Institutes of Sweden (SE)
- S** Silicon Austria (AT)
- T** Tampere University (FI)
Technische Hochschule Nürnberg Georg Simon Ohm (DE)
Technische Universität Chemnitz (DE)
Technische Universität Darmstadt IDD (DE)
Technische Universität Dresden - IAPP (DE)
Tekniker (ES)
- U** Universitat Politècnica de València, (ES)
Universität zu Köln (DE)
University of West Bohemia – RICE (CZ)
University of Bordeaux (FR)
University of Novi Sad – Faculty of Technical Sciences (CS)
University of Pardubice (CZ)
- V** Vito (BE)
VTT - Technical Research Centre of Finland (FI)
- W** WCPC - Swansea University (GB)
- Y** Yamagata University (JP)